

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("20050005436").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/03 08:51
S2	5160026	first or plural or multiple	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 15:12
S3	2175417	layer or film or coat	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 15:12
S4	50061	S2 with S3 with circuit	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 15:28
S5	885	(427/96.1,97.1,97.6,99.2,103).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/31 15:23
S6	98	S4 and S5	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 15:28
S7	3668	S4 and (remove with substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 16:02
S8	12	S7 and S5	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 15:28
S9	11198	S4 and (remov\$3 with substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 16:03
S10	34	S5 and S9	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/31 16:27
S13	365266	integrated circuit	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 08:52
S14	151880	remov\$3 with substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 08:52
S15	41169	S13 and S14	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 08:53
S16	6439	S13 same S14	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 08:53
S18	885	(427/96.1,97.1,97.6,99.2,103).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/03 13:02

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S19	68	S18 and S15	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 08:53
S20	1168	(427/96.1,97.1,97.6,99.2,103,96.2, 97.9).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/03 16:20
S21	131390	multilayer\$3 or layering	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:03
S22	2036882	circuit or circuitry or wiring	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:04
S23	70565	encapsulating or (conformal coating)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:10
S24	138637	(printed circuit board) or (printed wiring board)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 12:56
S25	3	S20 and ((S22 or S24) same S21) and S23	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:07
S26	204194	encapsulat\$3 or (conformal coating)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:10
S27	3493962	microvia or via or hole or notch\$2 or trench\$2 or cavit\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:11
S28	10432	S27 and S21 and S24	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 14:42
S29	79	S28 and S20	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:41
S30	14	S29 and (remove with substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 13:42
S31	19158	S27 and S21 and (integrated circuit)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 14:43
S32	101	S31 and (remove substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 14:51
S33	5511	S31 and (remov\$3 with substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 14:51

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S34	14	S33 and S20	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 14:51
S35	1156	(427/96.1,97.1,97.6,99.2,103,96.2, 97.7).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/03 16:20
S42	11	S35 and (peel\$3 or etch\$3 or remov\$3) and S21 and S26	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 16:27
S43	6	S35 and ((peel\$3 or etch\$3 or remov\$3) with (circuit or metal or conduct\$3)) and S21 and S26	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:05
S44	2220	(S24 or integrated circuit) and ((peel\$3 or etch\$3 or remov\$3) with (circuit or (thin metal foil) or substrate)) and S21 and S26	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:09
S49	4621	(S24 or (integrated circuit)) and ((peel\$3 or etch\$3 or remov\$3) with (circuit or (thin metal foil) or substrate)) and (S21 or multi\$1layer or (multiple near3 (circuit or metal or conduct\$3))) and S26	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:16
S50	4272	(S24 or (integrated circuit)) and ((peel\$3 or etch\$3 or remov\$3) with (circuit or (thin metal foil) or substrate)) and (S21 or multi\$1layer or (multiple near3 (circuit or metal or conduct\$3))) and S26 and S27	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:17
S51	2167	((S24 or (integrated circuit)) same S27) and ((peel\$3 or etch\$3 or remov\$3) with (circuit or (thin metal foil) or substrate)) and (S21 or multi\$1layer or (multiple near3 (circuit or metal or conduct\$3))) and S26	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:18
S52	98	S51 and "427".clas.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/03 17:26
S53	4	((("4,897,676") or ("5,716,663") or ("5,747,222") or ("6,200,405")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/03 17:27
S54	38	("5716663").URPN.	USPAT	ADJ	ON	2006/04/04 09:33
S55	16	("5948533").URPN.	USPAT	ADJ	ON	2006/04/04 12:54
S57	459779	(printed circuit board) or (printed wiring board) or (integrated circuit)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 12:57

EAST Search History

S58	18018	S57 with thin	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 12:57
S59	1157	(427/96.1,97.1,97.6,99.2,103,96.2, 97.7).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/04 12:57
S60	77	S58 and S59	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 12:57
S64	166404	(peel\$3 or remov\$3) with (substrate or (thin near5 metal))	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 15:37
S65	43	S59 and (S64 same S57)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:06
S66	19058	peel\$3 with (substrate or (thin near5 metal))	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:05
S67	50	S59 and S66	USPAT	ADJ	ON	2006/04/04 13:23
S68	24666	release near3 layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 14:26
S69	14	S59 and S68 and circuit	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 14:43
S70	84	tin near5 paste near5 layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 14:56
S71	3	S70 and "427".clas.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 14:44
S72	238879	multilayer\$3 or multi\$1layer\$3 or (multiple layer)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 14:58
S73	54745	S57 and S72	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 15:38
S77	4	S73 and S59 and S68	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 15:12
S78	18	S73 and S59 and S66	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 15:36
S79	404270	dimple or depression or indentation	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 15:36

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S80	964325	(substrate or (thin near5 metal))	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 16:47
S81	10	S57 and S59 and (S79 with S80)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 16:48
S83	4	((("6,220,934") or ("6,234,875") or ("5,972,792") or ("5,759,427"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/04 16:21
S84	1	S83 and S79	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 16:39
S87	2515030	metal	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 16:48
S88	3	S57 and S59 and (S79 with S87)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 16:48
S89	40475	peel\$3 with (metal or film)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:15
S90	9	S59 and (S89 same S57)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:06
S91	259752	(remov\$3 or peel\$3) near3 (metal or film or substrate)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:16
S92	53483	S91 and S57	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:18
S93	8291	S91 same S57	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:16
S96	5860	S91 and (S57 same S72)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/04 17:18
S97	54	S96 and S59	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/05 08:50
S98	419966	multi\$1layer\$3 or interlayer\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 08:51

EAST Search History

S99	1310036	pcb or (circuit board) or pwb or (wiring board) or ic or (integrated circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 08:51
S10 2	286127	substrate near3 (temporary or transfer\$3 or peel\$3 or remov\$3 or separat\$3 or etch\$3 or sacrific\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 10:41
S10 4	6840852	via or hole or notch\$2 or groove or dimple or depression or indentation or blind or channel or trench\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:18
S10 5	406	S98 same S99 same S102 same S104	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 10:41
S10 6	2	"20030160339".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 09:50
S10 7	0	("2003/0160339").URPN.	USPAT	ADJ	ON	2006/04/05 09:53
S10 8	6	((("5200362") or ("5273938") or ("5977613") or ("6259022") or ("6437430") or ("6580161"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/05 09:54
S10 9	135347	substrate near (temporary or transfer\$3 or peel\$3 or remov\$3 or separat\$3 or etch\$3 or sacrific\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 10:41
S11 0	132	S98 same S99 same S109 same S104	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:29
S11 1	180349	electronic component	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 12:49
S11 2	32	S110 and S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 12:24

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S11 5	1147828	(electric component) or transistor or resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:27
S11 6	49	S110 and S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 12:50
S11 7	87730	((electr\$4 component) or transistor or resistor or inductor or capacitor) with lead	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:27
S11 8	804	(S98 same S99 same S104) and S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:30
S11 9	3905	((electr\$4 component) or transistor or resistor or inductor or capacitor) with lead with solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:29
S12 0	95	(S98 same S99 same S104) and S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:44
S12 1	147	(S98 same S99 same S104) same S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 13:30
S12 4	243864	encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:19
S12 5	151	S98 same S99 same S104 same S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:59
S12 6	9	S125 and S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:21

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S12 7	24	S125 and S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:21
S12 8	88	(S98 with S99) same S104 same S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 14:26
S12 9	154	S98 same S99 same S104 same (dimple or indentation or depression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 15:03
S13 1	22	S98 same S99 same S104 same ((dimple or indentation or depression) with substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/05 15:24
S13 2	1	("20030160339").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/05 15:07
S13 4	1	("6495912").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/05 15:13
S13 6	49	S98 same S99 same S104 same ((flat or planar) near substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:25
S13 7	920999	(integrated circuit) or IC	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:34
S13 8	6845007	via or hole or notch\$2 or groove or dimple or depression or indentation or blind or channel or trench\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:28
S13 9	1038717	(electr\$4 or electrically) near (component or connect\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:29

EAST Search History

S14 0	420295	multi\$1layer\$3 or interlayer\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 16:48
S14 2	1857241	(solder with tin) or wir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:37
S14 3	1479	(S137 same S138 same S140) and (S139 same S142)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 14:53
S14 4	444	S137 same S138 same S140 same S139 same S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 13:58
S14 5	8	(S137 same S140 same ((flat or planar) near substrate)) and (S139 same S142)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 14:03
S14 7	0	(S137 same S138 same S140) and (S139 same (solder with tin) same short)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 14:55
S14 8	0	(S137 same S138 same S140) and (S139 same (solder with tin) same short\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 14:55
S14 9	50	(S137 same S138 same S140) and (S139 same solder same short\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:30
S15 0	150384	(hole or notch\$2 or groove or dimple or depression or indentation or blind or channel or trench\$2) near2 (substrate or film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:29
S15 1	1311007	pcb or (circuit board) or pwb or (wiring board) or ic or (integrated circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:31

EAST Search History

S15 2	1162	S151 same S138 same S140 same S150	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:32
S15 3	70	S152 and ("427"/\$.ccls. or 228/180. 1.ccls. or 29/840.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/06 16:36
S15 4	2	((("5,716,663") or ("5,747,222")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/07 10:37
S15 5	180	remov\$6 near2 ((copper or cu) substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 10:38
S15 6	110	S155 and (ic or integrated or printed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 11:09
S15 7	99	S155 and (ic or (integrated circuit) or (circuit board) or (wiring board) or pcb or pwb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 12:57
S15 8	1965639	ic or (integrated circuit) or (circuit board) or (wiring board) or pcb or pwb	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 11:12
S15 9	180	remov\$6 near2 ((copper or cu) substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 12:57
S16 0	47	S159 and (ic or (integrated circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/07 13:19

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S16 2	3	((("20020089053") or ("20010011767") or ("20030001932")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/07 13:22
S16 3	1	("2003/0001932").URPN.	USPAT	ADJ	ON	2006/04/07 13:34
S16 4	3	((("6543885") or ("6700184") or ("6194778")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/07 13:35
S16 5	2	("5632627" "6274057").PN. OR ("6543885").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/07 13:35
S16 6	13	("5136366" "5198883" "5255157" "5336931" "5355283" "5367191" "5554885" "5557150" "5683942" "5756377" "5773895" "5847446" "6240632").PN. OR ("6700184").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/07 13:37
S16 7	5	("6310304" "6329610" "6351031" "6399891" "6441314").PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/07 16:41
S17 5	1312446	pcb or (circuit board) or pwb or (wiring board) or ic or (integrated circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/11 08:20
S17 7	486539	multi\$1layer\$3 or interlayer\$3 or multilayer or (multiple layer\$3) or (alternat\$5 layer\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/11 08:21
S17 9	1881	(resin\$1copper) or (resin adj (copper or cu))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/11 08:22
S18 0	94	S179 same S175 same S177	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/11 08:24
S18 3	115	((Sn or tin) paste) or tin\$paste	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/11 14:16

EAST Search History

S18 4	1312446	pcb or (circuit board) or pwb or (wiring board) or ic or (integrated circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/11 14:17
S18 5	79	S184 and S183	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/11 14:25
S18 6	32	S184 and (S183 same solder)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/11 14:26
S18 7	1705	((solder ball) or (solder\$1ball)) same tin	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/12 09:06
S18 8	1312446	pcb or (circuit board) or pwb or (wiring board) or ic or (integrated circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/12 09:06
S18 9	486539	multi\$1layer\$3 or interlayer\$3 or multilayer or (multiple layer\$3) or (alternat\$5 layer\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/12 09:07
S19 0	47	S188 same S189 same S187	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/12 09:15